

HRC0202A

Silicon Schottky Barrier Diode for Rectifying

REJ03G0147-0600Z

(Previous: ADE-208-210E)

Rev.6.00

Nov.26.2003

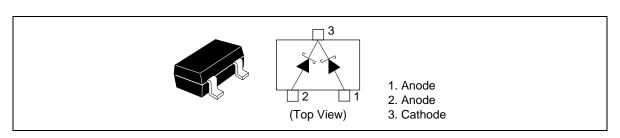
Features

- Low forward voltage drop and suitable for high efficiency rectifying.
- CMPAK Package is suitable for high density surface mounting and high speed assembly.

Ordering Information

Type No.	Laser Mark	Package Code
HRC0202A	S16	CMPAK

Pin Arrangement



Absolute Maximum Ratings *1

 $(Ta = 25^{\circ}C)$

Item	Symbol	Value	Unit	
Repetitive peak reverse voltage	V _{RMM} *1	20	V	
Average rectified current	l ₀ *2	200	mA	
Non-Repetitive peak forward surge current	I _{FSM} * ³	2	Α	
Junction temperature	Tj	125	°C	
Storage temperature	Tstg	-55 to +125	°C	

Notes: 1. Two device total

2. See from Fig.4 to Fig.7

3. 10ms sine wave 1 pulse

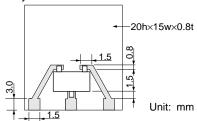
Electrical Characteristics *1

 $(Ta = 25^{\circ}C)$

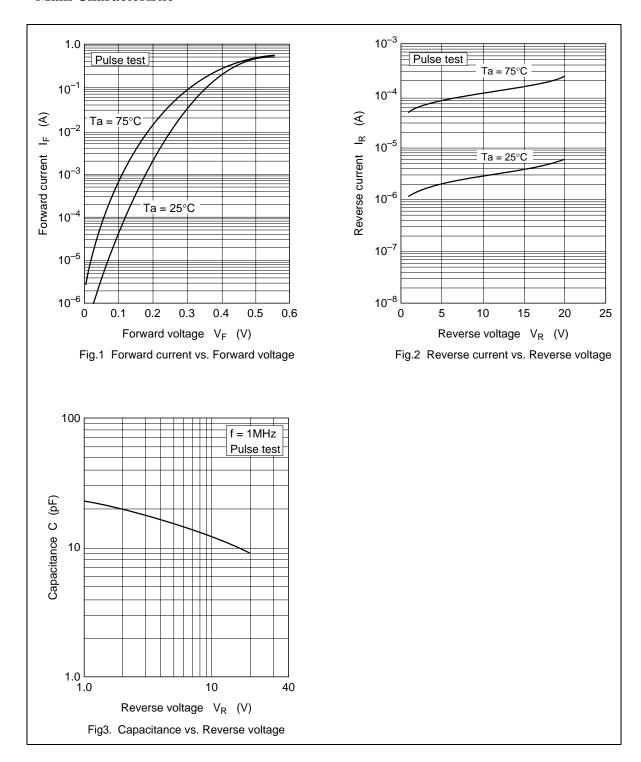
Item	Symbol	Min	Тур	Max	Unit	Test Condition
Forward voltage	V _F	_	_	0.40	V	I _F = 100 mA
Reverse current	I _R	_	_	50	μА	V _R = 20 V
Thermal resistance	R _{th(j-a)}	_	450	_	°C/W	Polyimide board ^{*2}

Notes: 1. Per one device

2. Polyimide board



Main Characteristic



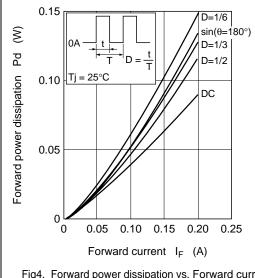


Fig4. Forward power dissipation vs. Forward current

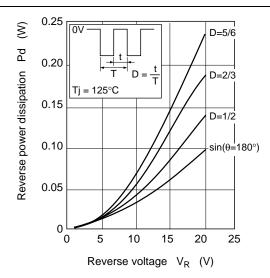


Fig5. Reverse power dissipation vs. Reverse voltage

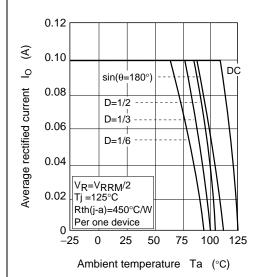


Fig.6 Average rectified current vs. Ambient temperature

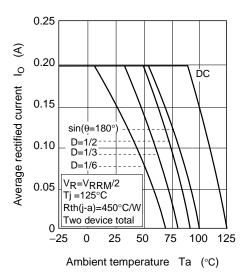
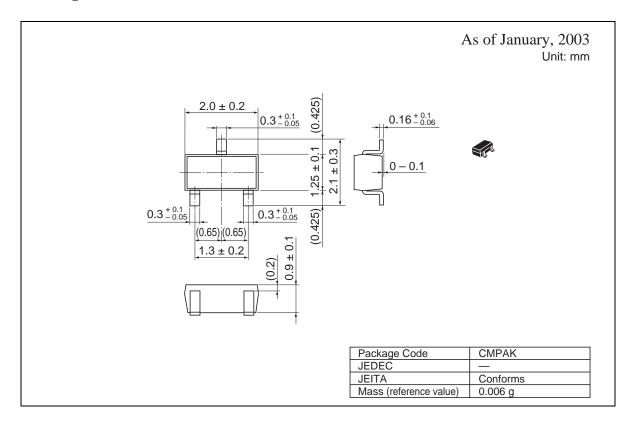


Fig.7 Average rectified current vs. Ambient temperature

Package Dimensions



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